



Blakely, Sokoloff, Taylor & Zafman LLP  
Title: High Performance Thermal Interface Curing Process for Organic Flip Chip  
Packages  
1st Named Inventor: Nagesh Vodrahalli  
Application No.: 09/475,104  
Sheet: 1 of 1

(714) 557-3800

Docket No.: 42390P6785

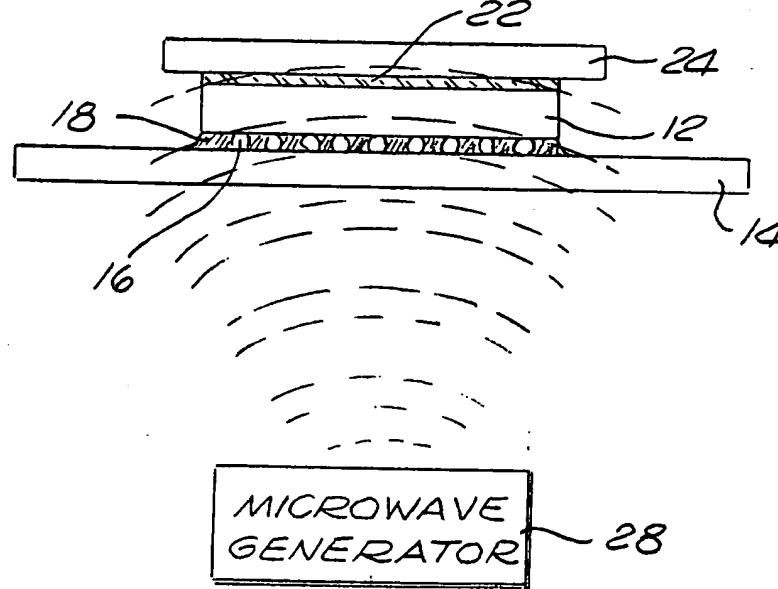
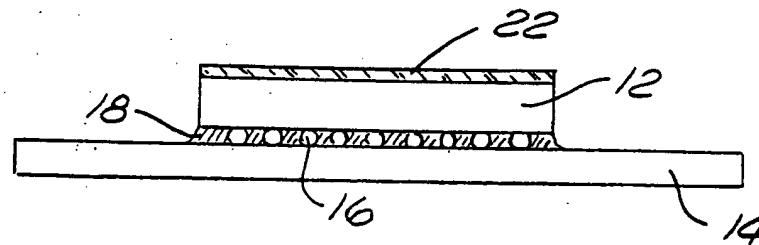
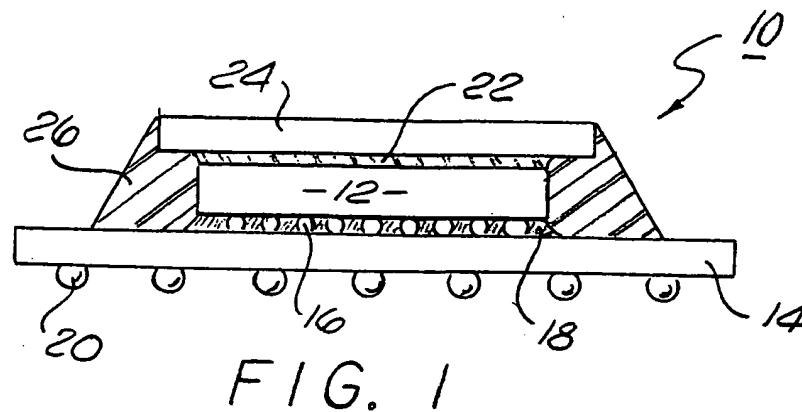


FIG. 2b